

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

	Stephan Grunow, et al.	Docket No.:	TI-35917
Serial No:	10/688,452	Art Unit:	3729
Filed:	10/18/2003	Examiner:	Rick K. Chang
Customer No.:	23494	Conf. No.:	1572
Title:	A Method of Forming a Stacked Interconnect Structure Between Copper Lines of a Semiconductor Circuit		

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AMENDMENT UNDER 37 CFR 1.111

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

CERTIFICATION OF TRANSMISSION

I hereby certify that the following papers are being electronically transmitted to the U.S. Patent and Trademark Office on 11/6/2006.

/Jacqueline J Garner/  
Jacqueline J. Garner  
Reg. No. 36,144

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated May 4, 2006. They are respectfully submitted as a full and complete response to that Action.

Please amend the above-referenced application as follows:

The **Amendments to the Specification (Title)** begin on page 2.

**Amendments to the Claims** are reflected in the listing of claims that begin on page 3 of this paper.

There are no **Amendments to the Drawings**.

The **Remarks** begin on page 6.